

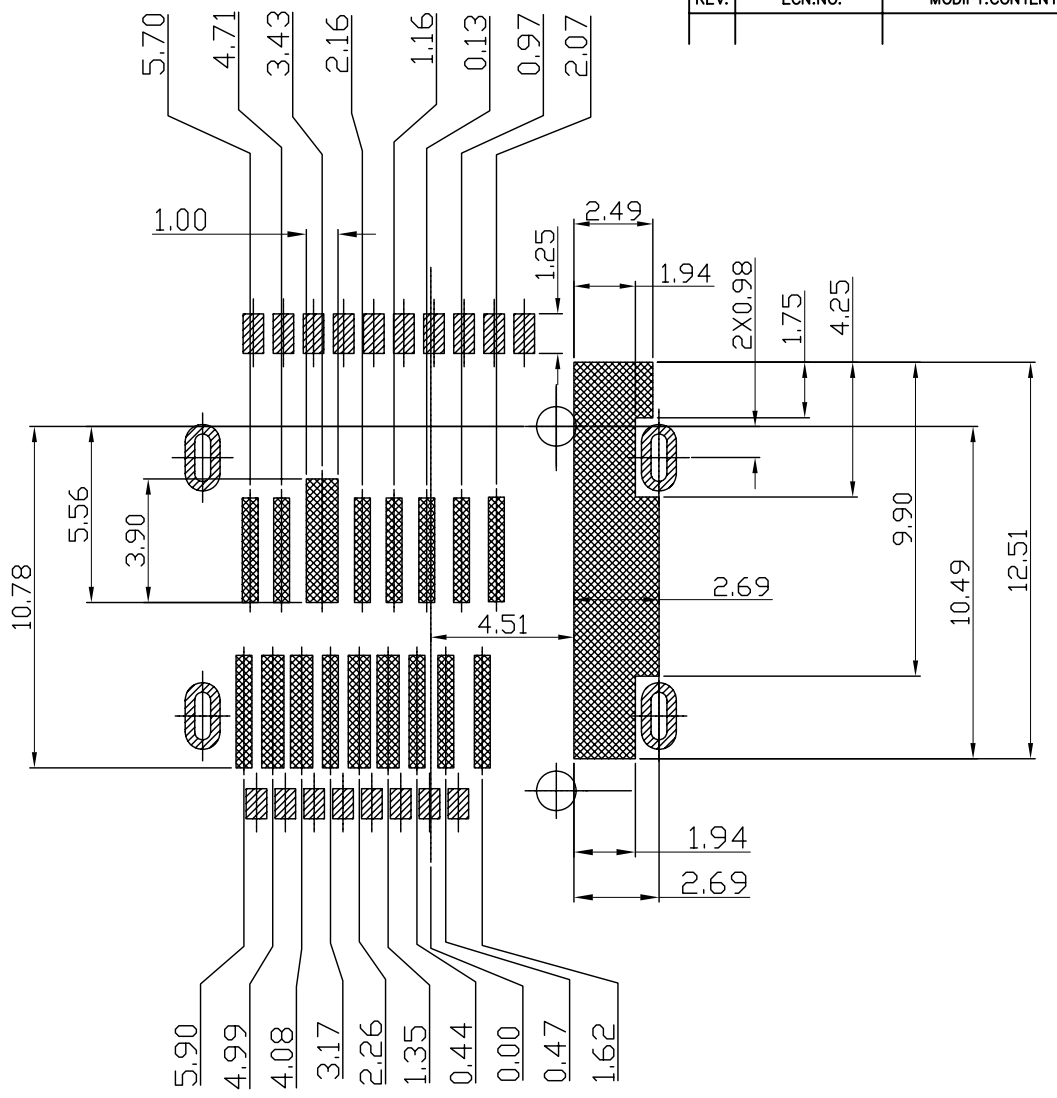
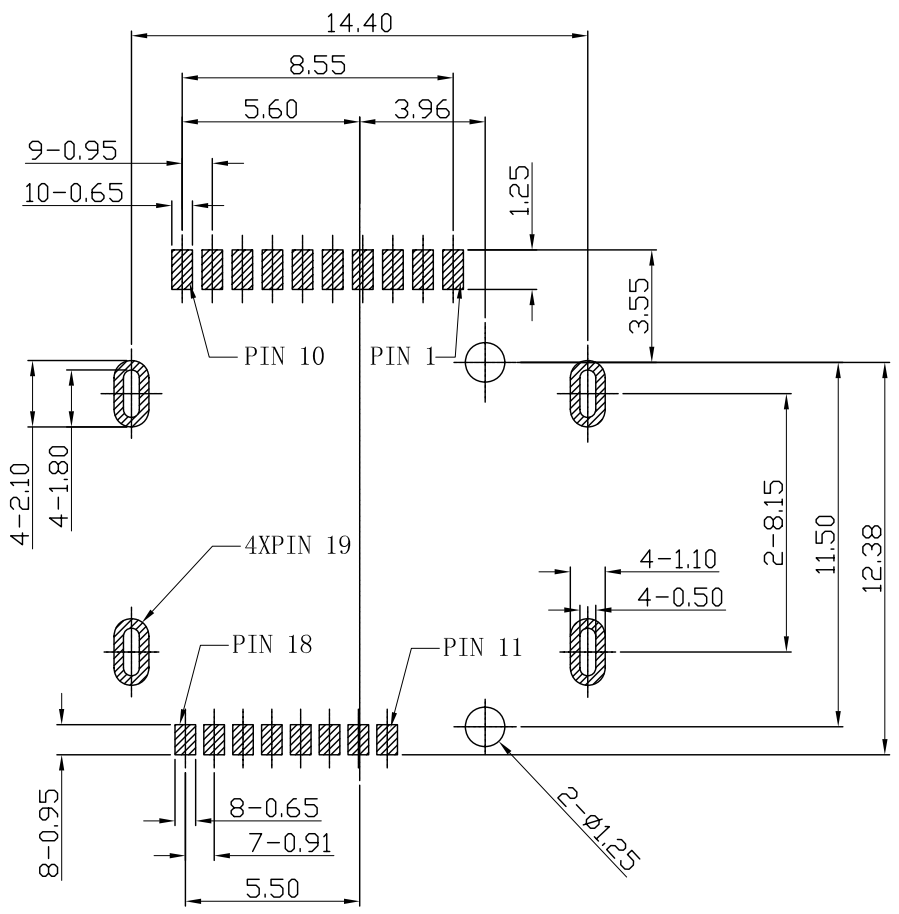
PART.NO.:
MR113-AP401-**

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少80U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少80U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少80U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少80U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少80U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少80U"

GENERAL TOLERANCE	DWG.NO.	MR113-AP401-00	PART.NO.	MR113-AP401-**	DRAWN	L.M.J 2017.07.15
x.±0.50	REV.	A	TITLE	Micro SD4.0 PUSH H1.50 conn	CHECKED	
.x±0.25	SIZE	A4	SHEET	1 OF 4	APPROVED	
.xx±0.15						

UNIT	mm	SCALE	1:1
 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

REV.	ECN.NO.	MODIFY.CONTENT
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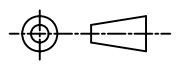
PCB PATTERN LAYOUT

(GENERAL TOLERANCE: ±0.05)

- PAD
- NO trace, NO test point
NO via hole, NO ground area

GENERAL TOLERANCE	DWG.NO.	PART.NO.	DRAWN
x.±0.50	MR113-AP401-00	MR113-AP401-**	L.M.J 2017.07.15
x.°±5°	REV.	TITLE	CHECKED
.x±0.25	A	Micro SD4.0 PUSH H1.50 conn	
.x°±2°	SIZE	SHEET	APPROVED
.xx±0.15	A4	2 OF 4	

UNIT	mm	SCALE	1:1
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Pin Define

Connector PinNo.	MicroSD 4.0 Card Pin No.	Micro SD with UHS-II and SWIO support		
		Name	Type	Description
P1	P9	V _{DD2}	S	Supply voltage(1.8V)
P2	P1	DAT2	I/O	Data Line[Bit 2]
P3	P2	CD/DAT3	I/O	Card Detect/Data Line[Bit 3]
P4	P3	CMD	I/O	Command/Response
P5	P4	V _{DD1}	S	Supply voltage(3.3V)
P6	P5	CLK	I	Clock
P7		CD		
P8	P6	V _{SS}	S	Supply voltage ground
P9	P7	DAT0/RCLK+	I/O	Data Line[Bit 0]/RCLK+
P10	P8	DAT1/RCLK-	I/O	Data Line[Bit 1]/RCLK-
P11	P17	SWIO	I	Single Wire Protocol Interface
P12	P10	V _{SS}	S	Supply voltage ground
P13	P11	D0+	I/O	UHS-II D0+
P14	P12	D0-	I/O	UHS-II D0-
P15	P13	V _{SS}	S	Supply voltage ground
P16	P14	D1-	I/O	UHS-II D1-
P17	P15	D1+	I/O	UHS-II D1+
P18	P16	V _{SS}	S	Supply voltage ground
P19	GND		GROUND	

NOTES :

1. MATERIAL :

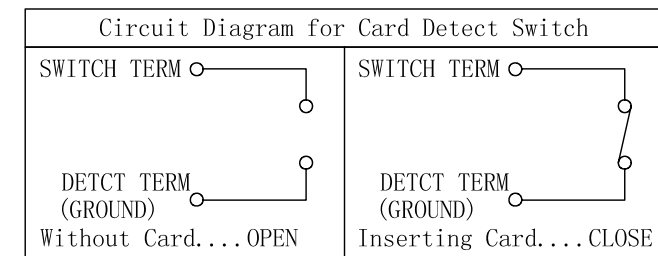
- 1.1 HOUSING:LCP UL94 V-0, BLACK COLOR.
- 1.2 SHELL: STAINLESS STEEL
- 1.3 CONTACT: COPPER ALLOY


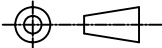
2. FINISH :

- 2.1 CONTACT: GOLD PLATING ON CONTACT AREA,
MATTE TIN 80u"MIN ON SOLDERTAIL AREA.
50u" MIN NICKEL PLATING OVERALL.
- 2.2 SHELL: 30u" MIN NICKEL PLATING OVERALL.

3. ELECTRICAL CHARACTERISTICS:

- 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
- 3.2 CURRENT RATING : 0.5 A.
- 3.3 OPERATING TEMPERATURE: -25°C~+85°C.
- 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
- 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
- 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.



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.x±0.50	x. °±5°	REV.	A	TITLE	Micro SD4.0 PUSH H1.50 conn	CHECKED		 OLN 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x °±2°	SIZE		SHEET	3 OF 4	APPROVED					
.xx±0.15	.xx°±1°	A4									

东莞市欧联电子科技有限公司

包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

一.

- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
- 2) 包装时,如下图所示.
- 3) 一个REEL包装盘放置800个成品.

二.

- 1) 装盘前先把前面空10格,然后再开始装盘, 尾端也需空出10格,上带加长200mm.
- 2) 装满成品的REEL包装盘如下图所示.

三.

- 1) 每箱装 8 盘REEL包装盘.
- 2) 每箱放置 6400 PCS 的成品.

REEL盘

四.

- 1) 用TAPE将纸箱封实.

備註 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

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x. ±5°	REV.	TITLE	CHECKED
.x ±0.25	A	Micro SD4.0 PUSH H1.50 conn	
.x ±2°	SIZE	SHEET	APPROVED
.xx ±1°	A4	4 OF 4	

UNIT	mm	SCALE	1:1
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